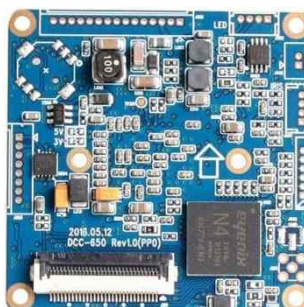
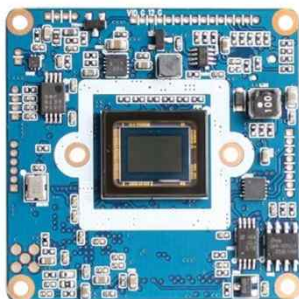


DCC-6510

CMOS VIDEO MODULE



Main Features

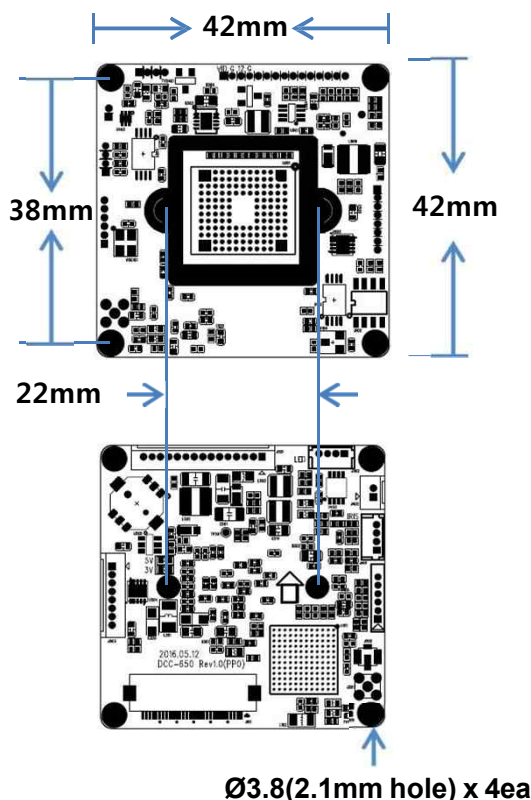
- 1/1.9" 2.12M(1080P) Sony CMOS Image Sensor
- 2Mega Pixels (1080P25/30/50/60, 720P25/30/50/60)
- Mountable Lens: Fixed, Auto VF, Auto ICR VF, Auto Focus Lens
- TDN ICR Mechanism Available
- WDR / 3D-NR / DSS(Sens-up)Supported
- 1080p Digital Video (BT.1120) Out via I²C & UART Control
- Parantek KP and Pelco-D Protocol Compatible
- Analog Composite Video Out
- CMOS HD-SDI Video Module (42x42 1-board)



Specifications

Model	DCC-6510
Signal System	Digital (BT.1120)
Pickup Device	1/1.9"(D-8.58mm) 2.12M SONY CMOS Sensor
Scanning System	Progressive Scan (16:9)
Sync. System	Internal
Total Pixels	2.42M [1952(H)x1241(V)]
Effective Pixels	2.12M [1937(H)x1097(V)]
Scanning Frequency	30Hz(VD) for NTSCout 25Hz(VD) for PAL out
Min. Illumination	0.02Lux(F2.5 – 30IRE), 0.01(ICR on), 0.0006Lux(DSS on)
Mechanical ICR	Available (Option)
H-Resolution	More than 1,000TV Lines(H)
S/N Ratio	More than 50dB (AGCoff)
Video Out 1	BT.1120 - 1080p@25/30/50/60, 720p@25/30/50/60 (0.5mm pitch 30pin FPC/FFC Connector)
Video Out 2	Composite Video 1V p.p (NTSC/PAL - 75Ω)
Lens	Auto Focus Lens, DC Auto & Fixed Iris Lens
Lens (Mount)	Board (M12) and VF (Ø14) – Lens Holder
OSD	Option (5-direction OSD Switch)
Camera Title	Off, On(Max. 8 Characters)
Language	English, Chinese(Simplified), Chinese(Traditional), Japanese, Korean
Exposure	DC, Manual
White Balance	AWB, ATW, Push Lock, Manual
BLC	Off, HLC, BLC, WDR * WDR is not operated when manual shutter mode or CVBS output mode is selected.
Day & Night Mode	AUTO, COLOR, B/W, EXT
Gain Control	AGC (0~10)
Electronic Shutter	1/25(30)~1/30,000sec
Noise Reduction	3DNR (Off, Low, Middle, High)
DSS(Sens-up)	X32
Mirror	Off, On(Mirror, Flip)
Other Features	Motion Detection (4 Zones), Privacy Mask (16 Zones), Flickerless, Lens Shading, Gamma, D-zoom, Defog etc.
Control	I ² C or UART
Protocol	Parantek KP Serial Protocol & Pelco-D Supported
Power Source	DC12V
Power Consumption	Less than 2.2 Watts (180mA)
Operating Temp.	-10℃ ~ 55℃ (Humidity :0%RH ~ 90%RH)
Size (mm)	42(W) x 42(D) – 1 board
Weight	10 g (Including OLPF)

Dimension



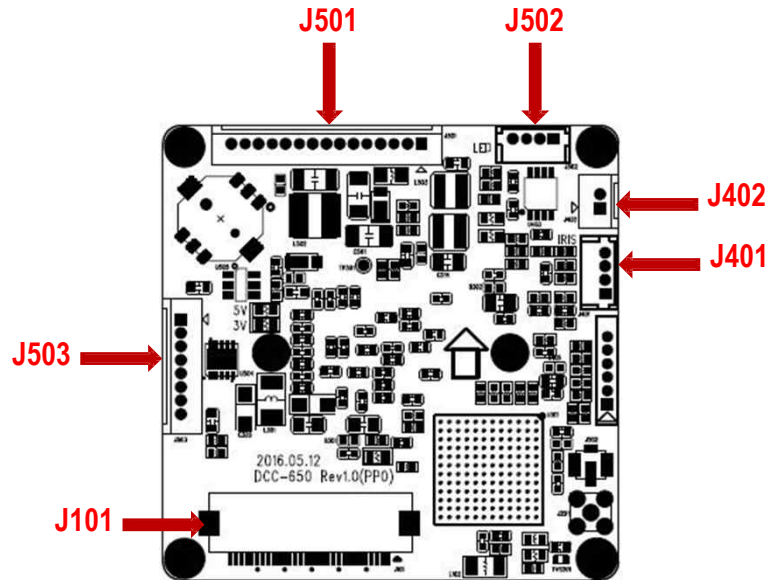
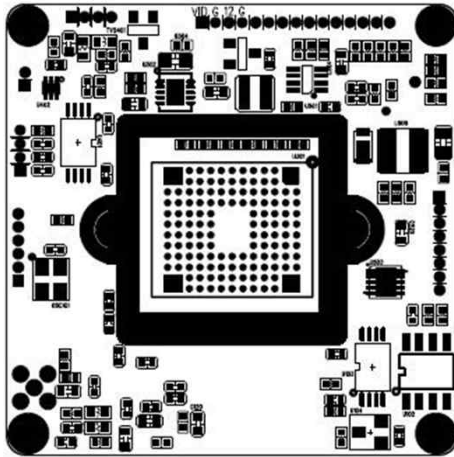
Option

- Mechanical TDN ICR
- OSD Switch
- Lens

DCC-6510

CMOS VIDEO MODULE

Pin Connections



J503 – 2Motor Drive

1 2 -- 7 8

No.	Pin Item	No.	Pin Item
1	Focus A-	5	Zoom B+
2	Focus A+	6	Zoom B-
3	Zoom A-	7	Focus B-
4	Zoom A+	8	Focus B+

Wafer DIP type: 1.25mm pitch – 8pin

Manufacturer: **Yeonho**

MFG Part Number: **12512WS-08B**

J502 – IR LED Board

1 2 3 4

No.	Pin Item	No.	Pin Item
1	DC12V	3	EXT_DN (CDS)
2	GND	4	D&N OUT

Wafer DIP type: 1.25mm pitch – 4pin

Manufacturer: **Molex**

MFG Part Number: **53047-0410**

J501 – Multi Ports

1 2 3 -- 13 14 15

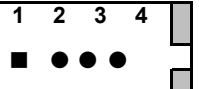
No.	Pin Item	No.	Pin Item
1	CVBS (Out)	9	OSD Key (Left)
2	GND	10	EXT DN (B/W:High 3.3V)
3	DC12V (In)	11	D&N Out (B/W:High 3.3V)
4	GND	12	RS485 TTL 3.3V TXD
5	OSD Key (Down)	13	RS485 TTL 3.3V RXD
6	OSD Key (Up)	14	RS485 TTL 3.3V CTL
7	OSD Key (Set)	15	DC 3.3V
8	OSD Key (Right)		

Wafer DIP type: 1.25mm pitch – 15pin

Manufacturer: **Yeonho**

MFG Part Number: **12512WS-15B**

J401 – DC IRIS



No.	Pin Item	No.	Pin Item
1	DMP+	3	DRV+
2	DMP-	4	GND

Wafer DIP type: 1.25mm pitch – 4pin

Manufacturer: **Molex**

MFG Part Number: **53047-0410**

J402 – TDN ICR

1 2

No.	Pin Item	No.	Pin Item
1	ICR (+)	2	ICR (-)

Wafer DIP type: 1.25mm pitch – 2pin

Manufacturer: **Yeonho**

MFG Part Number: **12512WS-02B**

J101 – BT.1120 & Etc.

No.	Pin Item	No.	Pin Item
1	Y0 (Out)	16	C7 (Out)
2	Y1 (Out)	17	HSYNC (Out)
3	Y2 (Out)	18	VSYNC (Out)
4	Y3 (Out)	19	GND
5	Y4 (Out)	20	Pixel Clock (Out)
6	Y5 (Out)	21	GND
7	Y6 (Out)	22	MD_Out (Out)
8	Y7 (Out)	23	N/C
9	C0 (Out)	24	SDA (In/Out)
10	C1 (Out)	25	SCL (In)
11	C2 (Out)	26	GND
12	C3 (Out)	27	GND
13	C4 (Out)	28	N/C
14	C5 (Out)	29	GND
15	C6 (Out)	30	Reset (In)

Wafer SMD type: 0.5mm pitch – 30pin

Manufacturer: **Yeonho**

MFG Part Number: **05002HR-H30J05**